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Vishay Siliconix

# N-Channel 100 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$V_{DS}$ (V) $R_{DS(on)}$ ( $\Omega$ ) MAX.		Q <sub>g</sub> (TYP.)		
100	0.0089 at V <sub>GS</sub> = 10 V	50	33 nC		
	0.0093 at V <sub>GS</sub> = 7.5 V	50	33 110		



## **Ordering Information:**

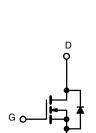
SUM70090E-GE3 (lead (Pb)-free and halogen-free)

#### **FEATURES**

- ThunderFET® power MOSFET
- Maximum 175 °C junction temperature
- Q<sub>gd</sub> / Q<sub>gs</sub> ratio < 1 optimizes switching characteristics
- 100 % R<sub>g</sub> and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

## **APPLICATIONS**

- Power supply
  - Secondary synchronous rectification
- DC/DC converter
- Power tools
- Motor drive switch
- DC/AC inverter
- Battery management



COMPLIANT

HALOGEN

**FREE** 

N-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-Source Voltage	V <sub>DS</sub>	100	V			
Gate-Source Voltage	V <sub>GS</sub>	± 20	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \			
Continuous Drain Correct /T 150 °C\	T <sub>C</sub> = 25 °C	,	50 °			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I <sub>D</sub>	50 <sup>c</sup>			
Pulsed Drain Current (t = 100 μs)	I <sub>DM</sub>	120	_ A			
Avalanche Current	I <sub>AS</sub>	40				
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	80	mJ		
Maximum Dawar Dissination 8	T <sub>C</sub> = 25 °C	В	125	١٨/		
Maximum Power Dissipation <sup>a</sup>	T <sub>C</sub> = 70 °C b	P <sub>D</sub>	87.5	W		
Operating Junction and Storage Temperature Ra	T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C			

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	LIMIT	UNIT		
Junction-to-Ambient (PCB Mount) <sup>b</sup>	R <sub>thJA</sub>	40	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	1.2	]		

#### Notes

- a. Duty cycle  $\leq 1 \%$ .
- b. When mounted on 1" square PCB (FR4 material).
- c. Package limited.



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100	-	-	V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	2	-	4	]	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	± 250	nA	
		V <sub>DS</sub> = 100 V, V <sub>GS</sub> = 0 V	-	-	1	μА	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS}$ = 100 V, $V_{GS}$ = 0 V, $T_J$ = 125 °C	-	-	150		
		$V_{DS} = 100 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 175 ^{\circ}\text{C}$	-	-	5	mA	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	50	-	-	Α	
Drain Course On State Resistance 3	J	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	0.0074	0.0089	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 7.5 V, I <sub>D</sub> = 15 A	-	0.0077	0.0093		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A	-	38	-	S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		-	1950	-	pF	
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 \text{ V}, V_{DS} = 50 \text{ V}, f = 1 \text{ MHz}$	-	845	-		
Reverse Transfer Capacitance	C <sub>rss</sub>		-	54	-		
Total Gate Charge <sup>c</sup>	$Q_g$		-	33	50	nC	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	8.8	-		
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$		-	7.5	-		
Gate Resistance	$R_g$	f = 1 MHz	0.7	3.5	7	Ω	
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>		-	15	30	- ns	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 50 \text{ V}, R_L = 5 \Omega$	-	27	54		
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D\cong 10~A,~V_{GEN}=10~V,~R_g=1~\Omega$	-	36	72		
Fall Time <sup>c</sup>	t <sub>f</sub>		-	45	90		
Drain-Source Body Diode Ratings ar	nd Characteri	stics <sup>b</sup> (T <sub>C</sub> = 25 °C)					
Pulsed Current (t = 100 μs)	I <sub>SM</sub>		-	-	120	Α	
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V	-	0.8	1.5	V	
Reverse Recovery Time	t <sub>rr</sub>		-	77	116	ns	
Peak Reverse Recovery Charge	I <sub>RM(REC)</sub>	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}$	-	4.2	6.3	Α	
Reverse Recovery Charge	Q <sub>rr</sub>		-	145	365	nC	

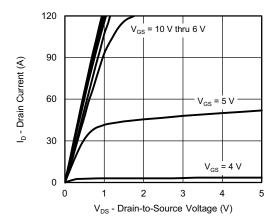
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

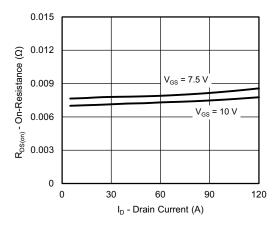
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



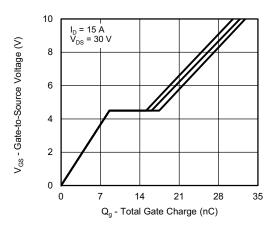
# **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



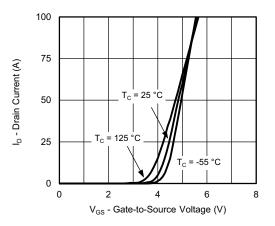
## **Output Characteristics**



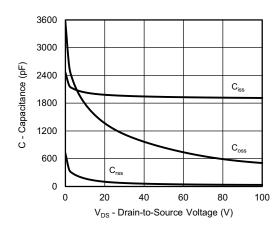
On-Resistance vs. Drain Current



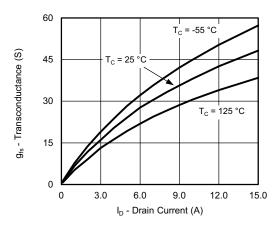
**Gate Charge** 



**Transfer Characteristics** 



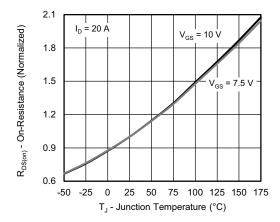
Capacitance



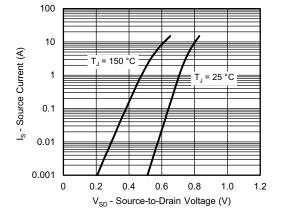
Transconductance



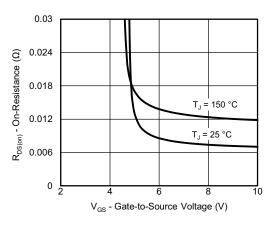
# **TYPICAL CHARACTERISTICS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



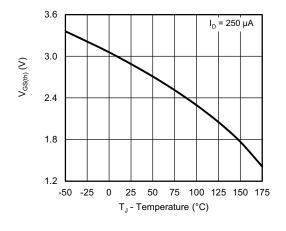
On-Resistance vs. Junction Temperature



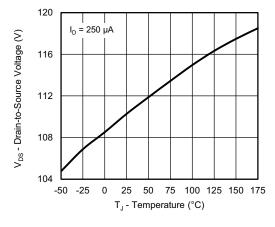
**Source Drain Diode Forward Voltage** 



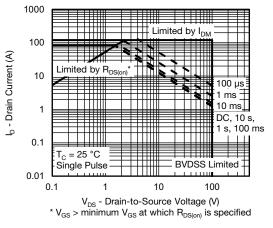
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



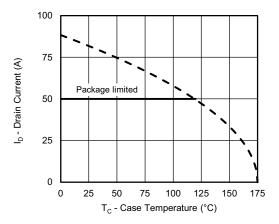
**Drain Source Voltage vs. Junction Temperature** 



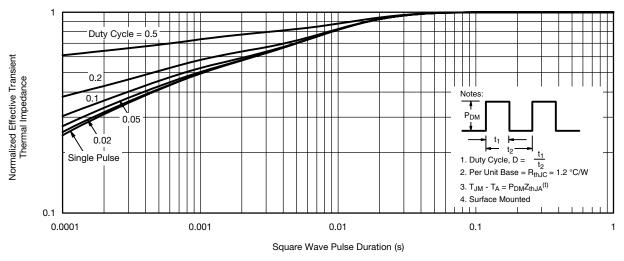
Safe Operating Area



# THERMAL RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)



## **Current De-Rating**



Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- · The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction to Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction to Case (25 °C)

are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board - FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?64432">www.vishay.com/ppg?64432</a>.



# TO-263 (D<sup>2</sup>PAK): 3-LEAD









DETAIL A (ROTATED 90°)



<u> </u>	b	<b>+</b> +
≥		<u>, o</u>
0	ECTION A	1

- 1. Plane B includes maximum features of heat sink tab and plastic.
- 2. No more than 25 % of L1 can fall above seating plane by max. 8 mils.
- 3. Pin-to-pin coplanarity max. 4 mils.
- 4. \*: Thin lead is for SUB, SYB. Thick lead is for SUM, SYM, SQM.
- 5. Use inches as the primary measurement.

6 This feature is for thick lead.

DIM.		INC	HES	MILLIMETERS		
		MIN.	MAX.	MIN.	MAX.	
Α		0.160	0.190	4.064	4.826	
	b	0.020	0.039	0.508	0.990	
	b1	0.020	0.035	0.508	0.889	
	b2	0.045	0.055	1.143	1.397	
c*	Thin lead	0.013	0.018	0.330	0.457	
	Thick lead	0.023	0.028	0.584	0.711	
c1	Thin lead	0.013	0.017	0.330	0.431	
CI	Thick lead	0.023	0.027	0.584	0.685	
	c2	0.045	0.055	1.143	1.397	
	D	0.340	0.380	8.636	9.652	
	D1	0.220	0.240	5.588	6.096	
	D2	0.038	0.042	0.965	1.067	
	D3	0.045	0.055	1.143	1.397	
	D4	0.044	0.052	1.118	1.321	
	Е	0.380	0.410	9.652	10.414	
E1		0.245	-	6.223	-	
E2		0.355	0.375	9.017	9.525	
	E3	0.072	0.078	1.829	1.981	
е		0.100	BSC	2.54 BSC		
K		0.045	0.055	1.143	1.397	
L		0.575	0.625	14.605	15.875	
L1		0.090	0.110	2.286	2.794	
L2		0.040	0.055	1.016	1.397	
L3		0.050	0.070	1.270	1.778	
L4		0.010 BSC		0.254 BSC		
	М	-	0.002	-	0.050	
ECN: T13-0707-Rev. K, 30-Sep-13						

DWG: 5843





# RECOMMENDED MINIMUM PADS FOR D<sup>2</sup>PAK: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index



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